Abstract—In industrial power electronic systems, power density and costs are key design criteria. Therefore, very high switching frequencies are commonly used in order to minimize the volume of the inductive components. However, especially in high-current applications, the well-known skin and proximity effects as well as the fringing field around the air gaps of inductors, impede the design of these components, as they are usually all reducing the effective cross-sectional area of solid inductor windings. Consequently, litz wire windings would have to be used, which is often impossible, mainly due to cost reasons. This paper introduces a new, simple and efficient approach on how to integrate inductor windings directly into the PCB, by mitigating the high-frequency losses due to a relocation of the air gap. In this way, its fringing field can be used to partly compensate the parasitic magnetic fields causing the skin and proximity effects. Hence, very low production costs and high power densities can be achieved. In a first step, simple design guidelines are derived and verified by means of simulations. Finally, a possible hardware implementation of the proposed concept is presented.

Index Terms—PCB inductor, air gap relocation, magnetic field compensation

I. INTRODUCTION

Inductors are used in a variety of electronic applications and especially in the area of power electronic converter systems, where they are usually employed as filter components in order to attenuate the switching frequency output voltage ripple, e.g. of buck converter topologies [1] [2]. Hence, the inductive components need to be designed in such a way that they can handle a certain required maximum output current, whereby an appropriate copper cross-section of the winding needs to be provided in order to limit the arising conduction losses in the inductor winding. However, especially in high-power low-voltage applications, these inductor currents can be huge and therefore large copper cross-sections $A_{cu}$, e.g. using wide copper bars and solid conductor windings, are required. To achieve a high power density, it is therefore important to obtain a homogeneous current density throughout $A_{cu}$, in order to optimally use the employed copper material and therefore maximize the effective copper cross-sectional area $A_{cu,eff}$ of the winding.

However, a homogeneous current density is difficult to achieve, since due to the high-frequency (HF) current components resulting from the switching frequency, different parasitic effects come into play, which deflect the current towards the surface or edges of the conductor and thereby reduce the effective $A_{cu,eff}$. These parasitic HF effects can be divided into three main components: First, the skin effect, which characterizes the impact of the magnetic field $H_{skin}$ of a HF current in a conductor on its own conductivity, second, the proximity effect, which describes the mutual influence of the magnetic fields $H_{prox}$ of multiple current carrying conductors on their individual current distributions and lastly the third component, which originates from the impact of the fringing field $H_{ag}$ around an air gap of the magnetic circuit on conductors in its near vicinity [3]. Hence, if $H_{ag}$ penetrates a conductive material, it induces eddy currents according to the well-known law of induction and therefore acts similar to the aforementioned proximity effect (cf. Fig. 1).

Fig. 1. Parasitic magnetic fields $H_{skin+prox}$ and $H_{ag}$ in a conventional arrangement of a PCB winding inductor, which are inducing eddy currents $I_{eddy}$ in the conductor and therefore increase the total conduction losses.

These effects can be minimized in wire-wound inductors using litz wire, where multiple insulated thin copper strands are twisted in prescribed patterns, such that the flux linkages of all strands are equalized. As a result, the current splits equally among the individual wire strands and due to their much smaller wire diameter the skin effect caused by $H_{skin}$ and the induced currents due to $H_{prox}$ and $H_{ag}$ in each strand can strongly be reduced [4]–[6].

Unfortunately, litz wire has some significant drawbacks compared to solid copper conductors. On the one hand, the copper fill factor is comparably poor, as a significant amount of the available wire cross-sectional area is wasted due to the spaces between the strands and the required insulation of each individual strand. On the other hand, the allowable
current density in litz wire is strongly limited due to its large thermal resistance orthogonal to the wire surface [7]. In cost driven applications, however, the most significant downside of litz wire windings is their price, since the costs per weight of litz wire are much higher than the ones of solid conductors [8]. Furthermore, the wire wrapping process and the termination of these windings are challenging and also increase the manufacturing costs.

In industrial applications, solid conductor windings, and especially PCB integrated windings, are therefore preferred, as they allow for much higher current densities (improved power density) and a cheap and simple manufacturing of inductors. However, as already mentioned, large conductive surfaces are prone to induced eddy currents due to external magnetic fields. For this reason, different approaches have been presented in literature, which all try to minimize the external magnetic fields penetrating the conductor. The most efficient approaches use two different concepts: The first option is to reduce the fringing field of the air gap by means of either using multiple smaller air gaps (quasidistributed air gap, cf. Fig. 2a) or by using a low permeability material (true distributed air gap, cf. Fig. 2b) [9]. Another possibility is to place the air gaps perpendicular (z-direction) to the conductor, such that the main component of the resulting fringing field is heading into x-direction and therefore does not penetrate the conductor perpendicular to its surface, i.e. in z-direction. Consequently, the HF losses due to the fringing field of the air gap can be minimized, as long as the distance between the air gap and the conductor is larger than a certain value [9]. However, the manufacturing of inductor cores with multiple air gaps and/or low permeability material is difficult and expensive, which is why a design with a single air gap is usually preferred in industrial applications. Furthermore, in the aforementioned considerations, the influence of the existing perpendicular skin and proximity fields are usually neglected, even though they lead to significant HF losses in a real conductor. For this reason, in this paper these fields are taken into account as well, in order to end up with an optimized inductor geometry that ensures an almost frequency-independent current distribution and therefore optimal utilization of the cross section of the conductor. Thus, minimal HF losses in the windings and a high suitability for real implementations in efficient, powerdense and cost driven applications are obtained. In Section II, all aforementioned magnetic field components are derived by means of analytical and numerical calculations and based on these derivations, a simple field compensation concept is introduced, which allows for partial active compensation of the skin and proximity fields in a straight conductor using the fringing field of a single air gap placed perpendicular to the conductor (cf. Fig. 2c). Hence, the AC resistance can be kept almost at the level of the DC resistance even for very high frequencies. In Section III, the concept is applied to a more practice-oriented circular conductor arrangement (cf. Fig. 2d) and simple design guidelines are provided. In Section IV, the influence of multiple parallel PCB layers on the applicability of the proposed concept is investigated in detail and an exemplary practical implementation of a PCB winding inductor is shown. Finally, Section V concludes the findings of this paper.

II. FIELD COMPENSATION IN STRAIGHT CONDUCTORS

The main challenge in the design of a highly efficient high-frequency (HF) inductor winding is the minimization of its AC resistance $R_{AC}$, which is the same as striving for an AC to DC resistance factor $F_R$ close to one:

$$F_R = \frac{R_{AC}}{R_{DC}} \text{ minimize } F_{R,\text{opt}} = 1. \quad (1)$$

Hence, assuming $F_R = 1$ and according to

$$P_{\text{cond}} = R_{DC} F_R I_{\text{rms}}^2 = \int_{\Omega} \frac{J(x,y,z)^2}{\sigma} \text{d}V, \quad (2)$$

the conduction losses in the winding do not change with frequency, what inherently implies that the current distribution $J(x, y, z)$ in a conductor should be frequency-independent as well. Thus, independent of the actual inductor geometry, the AC current density $J_{AC}$ should be equal to its DC equivalent $J_{DC}$ in order to minimize the AC-resistance $R_{AC}$ and therefore also the conduction losses. However, this is usually difficult to achieve, as various magnetic field components summarized to $H_{\text{eddy}}$ penetrate the conductor and induce eddy currents according to

$$\nabla \times \vec{E} = -\mu_0 \frac{\partial H_{\text{eddy}}}{\partial t}, \quad (3)$$
wherefore a current displacement and increased $F_R$ values result.

In the following, the different field components contained in $H_{eddy}$ are analyzed based on the example arrangement of Fig. 3a, and their effects on the current distribution $J(x, y, z)$ are discussed.

The considered geometrical arrangement comprises an infinitesimally long straight conductor, surrounded by a ferrite core with a single air gap perpendicularly arranged to the top surface of the conductor, as illustrated in Fig. 3a. The corresponding DC current density can be calculated according to

$$J_{DC}(x, z) = \frac{I_L}{h_{cu} \cdot b_w} \cdot \vec{e}_y,$$

where $h_{cu}$ denotes the thickness and $b_w$ the width of the copper track. However, in order to simplify the calculation of the various field components of $H_{eddy}$, it is assumed that the thickness $h_{cu}$ of the conductor is smaller than the skin depth of the considered frequency $f_{sw}$, whereby even for high-frequency currents a homogeneous current density in z-direction results. This assumption is usually valid for PCB integrated inductor windings, where the copper thickness of the PCB with 35μm..70μm is smaller than the skin depth. Thus, an equivalent line current density $J_{line}$ can be defined according to

$$J_{line}(x) = h_{cu} \cdot J_{DC}(x) = \frac{I_L}{b_w} \cdot \vec{e}_y,$$

emulating a current sheet with $h_{cu} \rightarrow 0$. In order to achieve the desired $F_R = 1$, the same constant line current density obtained with DC currents should also be achieved for HF currents, requiring zero time-varying magnetic field inside the conductor, as otherwise a current displacement would result (cf. (3)).

However, in the inductor arrangement at hand, there are always two main magnetic field components penetrating the conductor in z-direction. On the one hand, the magnetic skin field $H_{z,skin}$ (cf. Fig. 4a), which originates from the current in the conductor and can be calculated according to Ampere’s Law

$$H_{z,skin}(x) = \int_{-b_{we}}^{b_{we}} \frac{J_{line}}{2\pi(x - \alpha)} d\alpha$$

$$= \frac{I_L}{2\pi b_w} \left( \ln \left( x + \frac{b_w}{2} \right) - \ln \left( \frac{b_w}{2} - x \right) \right) \cdot \vec{e}_z.$$

On the other hand, the fringing field $H_{z,ag}$ around the air gap, which can be derived according to [10], or for small air gaps even easier based on Fig. 3b, where the fringing field is assumed to be generated by an equivalent current $I_{ag,eq} \approx 2I_L$ [11]. The z-component of this magnetic field can therefore be calculated according to

$$H_{z,ag}(x) = \frac{I_L}{\pi} \cdot \frac{x}{d_w^2 + x^2} \cdot \vec{e}_z,$$

as shown in Fig. 4a. As can be noticed, both field components $H_{z,skin}$ and $H_{z,ag}$ are heading into opposite directions, whereby a partial mutual compensation of these fields can be observed. Consequently, the fringing field $H_{z,ag}$ of the air gap counteracts the field of the skin effect $H_{z,skin}$, as the total magnetic field perpendicular to the conductor can be reduced

$$H_{z,tot}(x) = H_{z,skin}(x) + H_{z,ag}(x).$$

However, as illustrated in Fig. 4b, the quality of the compensation, i.e. the distribution of the current density $J_y$, highly depends on the distance $d_w$ between the conductor and the air gap, as for very small values of $d_w$, $H_{z,ag}$ overcompenates $H_{z,skin}$, whereby most of the current is attracted towards the middle of the conductor (dominating proximity effect), and for large values of $d_w$ an undercompensation results and the current is pushed towards the edges of the conductor (dominating skin effect). Hence, there is an optimum distance $d_{w,opt}$, where an almost homogeneous current distribution can be achieved and therefore a very low $F_R$ value close to one results.

There are different approaches to find this optimum value of $d_w$, as e.g. the finite element method (FEM), where the geometric arrangement of Fig. 3a is simulated for different values of $d_w$ and different frequencies $f_{sw}$. The resulting AC to DC resistance factors $F_R$ are shown in Fig. 5a, where two different regions can be defined: First, the proximity effect region for $d_{w,norm} < 0.5$, where the fringing field of the air gap pulls the current towards the center of the conductor and second, the skin effect region for $d_{w,norm} > 0.5$, where the fringing field of the air gap cannot compensate the skin field anymore and the current flows at the edges of the conductor only. In Fig. 5b, these two regions are depicted in more detail depending on the frequency $f_{sw}$ for different discrete distances $d_w$ at ▼...⑦. On the left side, the $F_R$-values for three different $d_{w,norm}$ at ▼...⑤ in the proximity region are shown. For low frequencies $f_{sw}$, the proximity losses are strongly increasing with $f_{sw}$, as

![Fig. 4. a) Magnetic fields $H_{z,skin}$, $H_{z,ag}$ and $H_{z,tot}$, where only their components perpendicular to the conductor surface, i.e. in z-direction, are considered. Additionally, $H_{z,skin}$ corresponds to a homogeneous current distribution in the conductor and $H_{z,tot} = H_{z,skin} + H_{z,ag}$. b) shows the resulting HF current densities $J_y$ for different distances $d_w$ between the air gap and the conductor.](image)
the current distribution is getting more and more triangularly shaped. However, the current is pulled towards a region with a very low perpendicular magnetic field $H_{z,tot}$ (cf. Fig. 4a), which is why the losses do no longer significantly increase with frequency, once all the current is in this "low-field-region".

On the right-hand side, the $F_{RI}$-values for the three different $d_{w,norm}$ at ①...⑥ in the skin region are shown. As the current is pushed towards the edges of the conductor, where the highest magnetic fields occur, the conduction losses are constantly increasing with frequency with the well-known $\sqrt{f_{sw}}$ dependency.

However, between the two regions, where the optimal air gap position can be found, the $F_{RI}$ value is less than 1.1 even for very high frequencies. Consequently, an almost homogeneous current density can be achieved, where $H_{z,tot}$ hardly affects the current distribution. As a result, a loss factor $F_H2$ can be introduced

$$P_{loss} \propto \int_V H_{z,tot}^2 dV \rightarrow F_{H2} = \int_V H_{z,tot}^2 dV,$$  \hspace{1cm} (9)

as the HF losses are directly proportional to the penetrating magnetic field, as long as the current distribution in the winding does not change significantly [12]. This simple $H^2$-loss factor can be used to accurately predict the optimal air gap position, without carrying out a time-consuming FEM optimization. In addition, for very simple geometries, the optimum air gap position can even be found analytically. For the arrangement at hand, the $H^2$-loss factor and the optimal air gap position $d_{w,opt}$ can be calculated based on (6)-(8) according to

$$F_{H2} = \int_V H_{z,tot}^2 dV \quad \text{minimize} \quad \frac{\partial}{\partial d_w} F_{H2} \bigg|_{d_{H2}} = 0 \quad \text{(10)}$$

and

$$\frac{\partial}{\partial d_w} F_{H2} = \frac{\partial}{\partial d_w} \int_V H_{z,tot}^2 dV$$

$$= \int_V 2H_{z,tot} \frac{\partial}{\partial d_w} H_{z,tot} dV$$

$$\rightarrow d_{w,opt} = \frac{b_w}{2}.$$  

Hence, the analytically derived optimal air gap position $d_{w,opt}$ coincides with the optimal position found based on FEM simulations (cf. Fig. 5a).

A possible practical implementation of a PCB winding inductor, using the proposed field compensation concept on straight winding sections, is shown in Fig. 6a. However, this design has significant drawbacks, as the end-winding sections are not covered by the air gap, hence the skin and proximity fields are not compensated anymore and the conduction losses in these sections significantly increase. In addition, the ratio between the winding length $l_{wc}$ and the core area $A_C$ is comparably poor compared to the circular arrangement shown in Fig. 6b. Assuming the same total core cross section $A_C$ in both designs, the ratio between the winding lengths can be calculated according to

$$L_w(k) = \frac{l_{wc}}{l_{wc}} = \frac{1 + k}{\sqrt{\pi k}},$$  \hspace{1cm} (12)

where $k$ denotes the ratio between the length and the width of the core cross section $A_C$ of Fig. 6a. Hence, the minimum ratio between the winding lengths can be found to be

$$\frac{\partial}{\partial k} L_w(k) \bigg|_{k=1} \frac{k-1}{L_w(1)} = \frac{2}{\sqrt{\pi}} > 1.$$  \hspace{1cm} (13)

Thus, even for the optimal value $k = 1$ (square cross section), the winding length of the rectangular core $l_{wc}$ is larger than $l_{wc}$. Consequently, the circular arrangement of Fig. 6b should be used in practical applications, as in addition to the reduced winding length, the circularly shaped winding and air gap allow to compensate the skin and proximity fields along the whole winding, whereby the aforementioned end-winding losses can be avoided. However, the circular shape of the conductor might influence the optimal air gap position, which will be investigated in the following section.
III. FIELD COMPENSATION IN CIRCULAR CONDUCTORS

Unlike in a straight conductor, the DC current density $J_{DC}$ in circular conductors is not homogeneous anymore and can be calculated according to

$$J_{DC}(r) = \frac{I_L}{r \cdot h_{cu} \cdot \ln \left( \frac{r_{out}}{r_{in}} \right)}, \quad (14)$$

as shown in Fig. 7a. Hence, as already mentioned in the previous section, the HF current density $J_{AC}$ should match $J_{DC}$ as closely as possible in order to achieve a low $F_R$ value. In the same figure, the current distribution $J_{AC}$ due to the skin effect only, thus without an air gap in the near vicinity of the conductor, is illustrated. The magnetic skin field $H_{z,skin}$ pushes the current towards the center of the inductor, whereby an increased $F_R$ value results, even for comparably low frequencies ($F_R = 1.43$ at 100 kHz). Therefore, the fringing field $H_{z,ag}$ of the air gap is again required to compensate $H_{z,skin}$ and to pull the current away from the center of the winding to match $J_{DC}$ as accurately as possible. The compensating effect of $H_{z,ag}$ is shown for two different air gap locations in Fig. 7b and 7c, respectively.

In Fig. 7b, the air gap is located in the optimal position for this circular geometry, whereby a very low value for $F_R(=1.04)$ results and $J_{AC,comp}$ hardly deviates from $J_{DC}$.

In Fig. 7c, the air gap is placed at the position which would be optimal for a straight conductor, hence in the middle of the track with a distance $z_{ag}$ of $\frac{b_w}{2}$ (11). However, this location is far from optimal, as an almost homogeneous current distribution is achieved, which does not correspond to $J_{DC}(r)$. Consequently, the optimal air gap positions in straight and circular conductors are different and need to be calculated separately.

Once again, there are two different options to find the optimal air gap position in a circular conductor. Either the time-consuming FEM simulation, whose results are shown in Fig. 8 for varying $z_{ag}$ and $r_{ag}$ values, where $z_{ag}$ denotes the distance between the conductor and the air gap and $r_{ag}$ the radial position of the air gap, or by using the previously introduced $H^2$-loss factor $F_{H^2}$, which is calculated based on the magnetic skin field $H_{z,skin}$ of the DC current distribution $J_{DC}(r)$ and the fringing field $H_{z,ag}$ around the air gap according to

$$J_{line}(r) = J_{DC}(r) \cdot h_{cu} = \frac{I_L}{r \cdot \ln \left( \frac{r_{in}}{r_{out}} \right)}, \quad (15)$$

$$F_{H^2}(\omega_{\text{ave}}) = \frac{I_L^2}{2} \cdot \sum_{n=1}^{N} \left( \frac{r_{ag,n}}{r_{in}} \right)^2 \cdot H_{z,ag}(\omega_{\text{ave}}(r_{ag,n})),$$

where $\omega_{\text{ave}}$ is the average angular frequency for a given radial position $r_{ag,n}$ and $N$ is the number of radial positions.

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where \( E(k^2) \) and \( K(k^2) \) denote the complete elliptic integrals of the first and second kind. The results are shown in Fig. 9, whereby a very close match between the results of the actual \( F_H \) values of Fig. 8 and the \( H^2 \)-loss factors \( F_{H^2} \) can be observed. Especially for locations \((r_{ag}, z_{ag})\) with the lowest \( F_H \) values, the curves are almost identical, which allows for accurately predicting the optimal position \((r_{ag,opt}, z_{ag,opt})\) within a fraction of the time it would take to simulate the geometry in a FEM software.

The benefit of the significantly reduced calculation time of the \( H^2 \)-loss factors cannot only be used for the previously shown straight and circular conductor arrangements, as the principle of calculating the optimal air gap position using the \( H^2 \)-loss factor is very general and can be applied to all kind of winding geometries, once the DC current distribution is known. However, in order to simplify the usage of this concept in practice, a general design guideline would be nice, which reduces the computational effort for the inductor designer. Fortunately, in the circular arrangement of Fig. 8, the optimal air gap positions change with the ratio of radii only and do not depend on their absolute dimensions, which is why the desired general design guideline for circular conductors can be calculated for all ratios of radii \( \frac{r_{ag}}{r_{out}} \). The resulting optimal air gap positions \((r_{ag,opt}, z_{ag,opt})\) are depicted in Fig. 10.

In order to illustrate the difference between the actual optimal air gap position for a circular conductor and the simplified calculation based on a straight conductor (11), the results of both calculation methods are shown. For \( \frac{r_{ag}}{r_{out}} > 0.5 \), the simplified calculation \( z_{ag,opt} = \frac{b_2}{2} \) and \( r_{ag,opt} = \frac{r_{ag} + r_{out}}{2} \) yields very good results, closely following the the optimum \( z_{ag,opt} \) and \( r_{ag,opt} \) obtained from (16) and (17), as the DC current density \( J_{DC}(r) \) in the circular conductor is almost homogeneous. However, for lower ratios of radii, the optimal air gap position should be chosen according to the solid lines depicted in Fig. 10, due to the inhomogeneity of \( J_{DC}(r) \).

So far, only a single layer conductor has been considered. However, in practice, inductor windings usually comprise multiple turns and multiple layers in order to achieve a certain required inductance. Therefore, it is crucial to investigate the applicability of the proposed concept to multilayer windings, in order to prove its suitability for practical applications. This will be done in the following section based on a three layer arrangement.

**IV. Multilayer Winding**

The multilayer arrangement of Fig. 11 comprises three PCB layers, which are all separated by thin FR4 layers (not shown in the figure). In order to calculate the \( F_H \) values of the three different conductors, the perpendicular magnetic fields in each layer have to be known. Thanks to the linearity of magnetoquasistatic field problems, the principle of superposition can be applied, where the magnetic fields of each source (conductors, air gap) are calculated independently and superimposed in the end. However, the calculation of the different field components is not trivial, as the complexity of the field problem is increased due to the additional dimension.
in $z$-direction. Hence, in general, the perpendicular magnetic field throughout the PCB is not constant anymore, whereby a two-dimensional field problem would have to be solved. In order to reduce the calculation complexity of the magnetic field problem, it is assumed that the mutual distance $d_L$ between the layers is much smaller than the width $b_w$ of the copper tracks and therefore a constant $z$-component of the magnetic field $H_{z,\text{skin}}$ throughout the height of the PCB can be presumed. However, in the multilayer arrangement at hand, the total appearing parasitic magnetic field $H_{z,\text{skin}+\text{prox}}$ in the PCB is now induced by multiple individual layers. Thus, the magnetic skin field $H_{z,\text{skin},1}$ for example, which is induced by the current $I_L$ in the top layer of the PCB, penetrates not only the top layer itself, but also the two remaining layers (middle and bottom) as proximity field $H_{\text{prox},1}$. The same holds true for $H_{z,\text{skin},2}$ and $H_{z,\text{skin},3}$, whereby the total parasitic magnetic field in each layer can be calculated by superposition according to

$$H_{z,\text{skin}} = H_{z,\text{skin},1} + H_{z,\text{skin},2} + H_{z,\text{skin},3}. \quad (18)$$

Assuming the same DC current distribution $J_{DC}(r)$ in all turns, the total skin field $H_{z,\text{skin}}$ can therefore be calculated based on (16), using the equivalent line current density $J_{\text{line}}(r)$:

$$J_{\text{line}}(r) = \sum_{i=1}^{3} J_{\text{line},i}(r) = \frac{3 \cdot I_L}{r \cdot \ln \left( \frac{r_{\text{out}}}{r_{\text{in}}} \right)}. \quad (19)$$

Thus, the magnetic skin field in a three-layer winding is equivalent to the magnetic field induced by a single conductor carrying three times the inductor current $I_L$.

For this reason, the $F_R$ value of each layer can be calculated separately according to Fig. 5, as the magnetic flux in the core and therefore the fringing field around the air gap $H_{ag}$ is excited by $N \cdot I_L = 3 \cdot I_L$ as well. However, as the minimum distance between the different PCB layers is limited by manufacturing constraints, they cannot all be placed in the optimal position $z_{ag,\text{opt}}$. Hence, two out of the three layers are either slightly under- or overcompensated as shown in Fig. 11. The non-ideal current densities of the two outer layers slightly affect their $F_R$ values as illustrated in Fig. 12, where the top layer ① lies within the proximity effect region and the bottom layer ③ in the skin effect region, respectively. However, as long as the distance between layers $d_L$ is much smaller than the widths $b_w$ of the copper tracks, the $F_R$ values of the different layers are almost the same and the calculated optimal air gap position of a single layer arrangement can also be applied to multilayer windings.

It needs to be mentioned, that the quality of the compensation highly depends on the ratio between $d_L$ and $b_w$, as for large $d_L$ values the simplified assumption of a constant vertical magnetic field throughout the PCB is not valid anymore. Hence, the full two-dimensional field problem needs to be solved, which is however out of the scope of this paper. Nevertheless, in most designs $d_L \ll b_w$ is ensured and the proposed field compensation concept achieves $F_R$ values close to one, even for multilayer windings. Thus, very efficient high frequency PCB winding inductors for all kinds of inductance values can be designed.

In Fig. 13, an exemplary practical implementation of such an inductor with a multilayer PCB winding is shown. It should be pointed out that, in order to minimize the termination losses in the inductor, it is crucial to terminate the winding in a coplanar way, so that a homogeneous current density in the connecting copper tracks is achieved. In addition, the transitions between the layers should be done by means of through-hole vias only, as the usage of blind and buried vias increases the manufacturing costs of PCB windings significantly.

V. CONCLUSION

In this paper, a new method of designing highly efficient high-frequency PCB inductor windings has been introduced, where the fringing field of a single air gap can be used...
in such a way, that the existing skin and proximity fields in a PCB inductor winding are largely compensated. Thus, compared to state-of-the-art solutions, the fringing field of an air gap is not avoided anymore, but rather used to actively compensate adverse high-frequency effects (“turn enemies into friends”). Furthermore, the difficult manufacturing of multi-air-gap and low-permeability cores can be avoided, as a certain magnetic fringing field is desired. Consequently, cost-effective and efficient PCB inductor windings can be designed based on the design guidelines shown in this paper. Additionally, the proposed \( H^2 \)-loss factor calculation method allows for a fast calculation of the optimal air gap position for all different kinds of geometries. Thus, the proposed field compensation concept is by far not limited to standard inductor arrangements as the ones shown in this paper.

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